PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	MDG/22/13388
1.3 Title of PCN	ASE Kaohsiung (Taiwan) LQFP7x7 and LQFP10x10 package capacity increase - on listed of products
1.4 Product Category	LQFP 7x7 & LQFP 10x10 listed products
1.5 Issue date	2022-04-29

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung Taiwan

4. Description of change		
	Old	New
4.1 Description	Back-end sources: - Stats ChipPAC Jiangyin China (JSCC)	Back-end sources: - Stats ChipPAC Jiangyin China (JSCC) - ASE Kaohsiung Taiwan - Additional source For more information, please refer to PCN13388 – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Lead color and surface finish change depending on leadfinishing. Package darkness changes depending on molding compound. Pin1 identifier can change in terms of form and positioning. Marking position and size could be different upon assembly site, without any loss of information.	

5. Reason / motivation for change	
5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change	
6.1 Description	Change is visible through assembly traceability plant, in the marking: - “GQ” and "GH" for Stats ChipPAC China - “AA” for ASE Kaohsiung Taiwan Please refer to PCN13388 – Additional information attached document.

7. Timing / schedule	
7.1 Date of qualification results	2022-04-14
7.2 Intended start of delivery	2022-07-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	13388 10548 MDG-MCD-RER1810 V5 -ASE Kaohsiung for LQFP 7x7_10x10_14x14_20x20 STM8L STM32 - evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2022-04-29

9. Attachments (additional documentations)
13388 Public product.pdf 13388 10548 MDG-MCD-RER1810 V5 -ASE Kaohsiung for LQFP 7x7_10x10_14x14_20x20 STM8L STM32 - evaluation report.pdf 13388 PCN13388_Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32G070CBT6	

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